

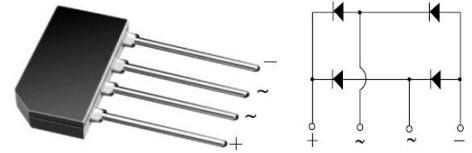


# SINGLE PHASE GLASS PASSIVATED BRIDGE RECTIFIER GBPC005 ~ GBPC110

## Single Phase Glass Passivated Bridge Rectifier

### Features

- Glass passivated chip junction
- Plastic package has underwriters laboratory
- Flammability classification 90V-0
- High cas dielectric with standing voltage of 1500Vrms
- Typical  $I_r$  less than 0.1 uA
- Ideal for printed circuit boards
- High surge current capability
- High temperature soldering guaranteed:  
260°C/10 seconds, 0.375"(9.5mm) lead length



Case Type GBL

### Mechanical Data

<b>Case:</b>	Molded Plastic body over passivated junctions
<b>Polarity</b>	/
<b>Terminals:</b>	Plated leads solderable per MIL-STD-750, Method 2026
<b>Mounting torque</b>	/
<b>Mounting position:</b>	Any (Note 1)
<b>Weight:</b>	0.1 ounce, 2.8 gram

### Maximum Ratings ( $T_{Ambient}=25^{\circ}C$ unless noted otherwise)

Symbol	Description	GBPC 1005	GBPC 101	GBPC 102	GBPC 104	GBPC 106	GBPC 108	GBPC 110	Unit	Conditions
VRRM	Max Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V	
VRMS	Max RMS Voltage	35	70	140	280	420	560	700	V	
VDC	Max DC Blocking Voltage	50	100	200	400	600	800	1000	V	
I(AV)	Max Average Forward Rectified Current	6.0/3.0							A	At TC= 60°C (note2) At TC= 25°C (note 3)
IFSM	Peak Forward Surge Current	175							A	8.3ms single half sine-wave (JEDEC method) TC= 260°C
TJ,TSTG	Operating and Storage Temperature Range	-55 to +150							°C	
I2t	Rating for Fusing	127							A2s	T<8.3mS

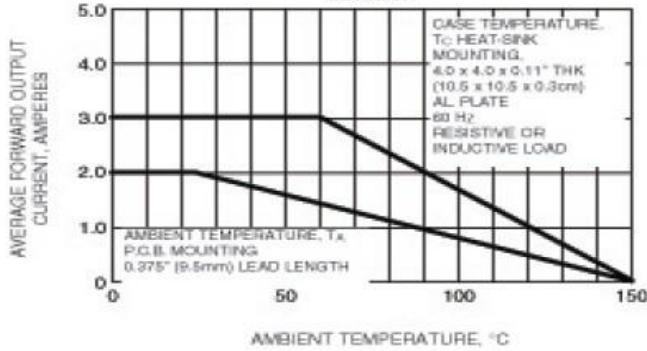
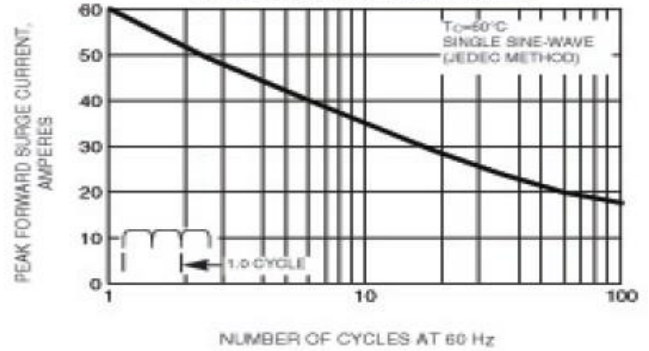
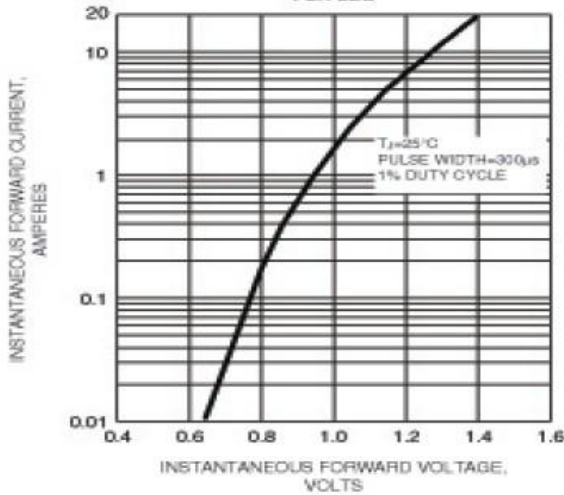
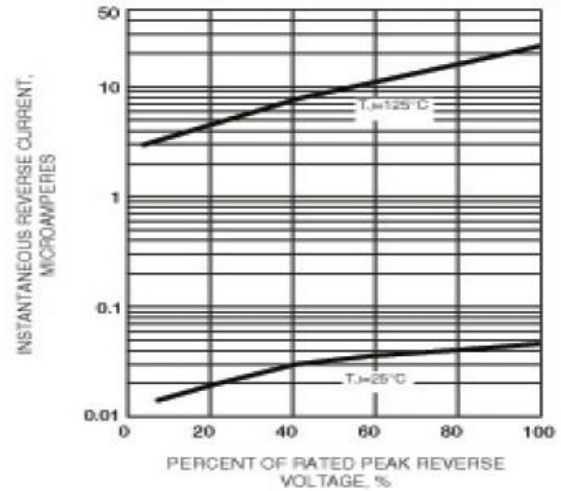
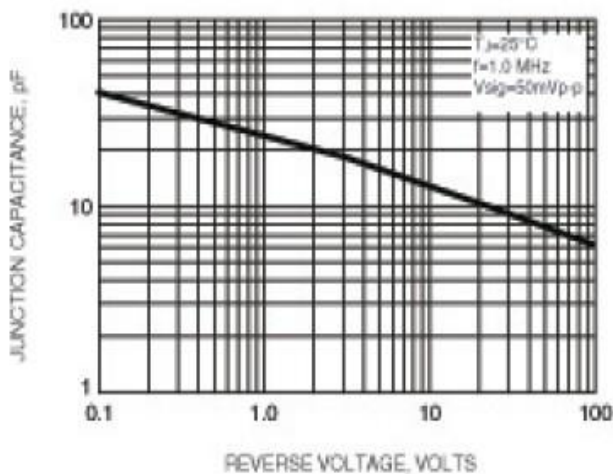
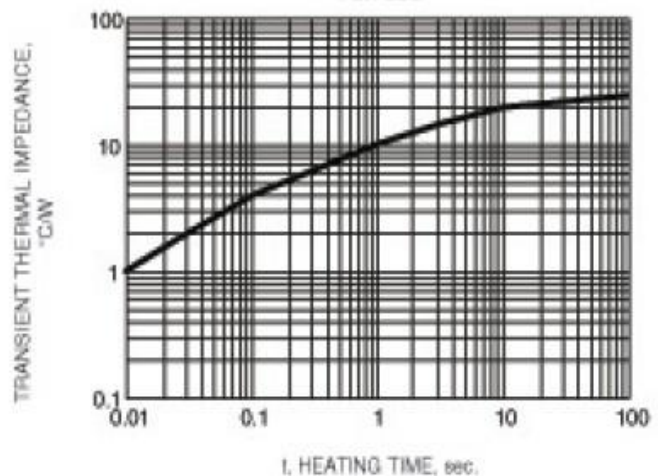
### Electrical Characteristics ( $T_{Ambient}=25^{\circ}C$ unless noted otherwise)

Symbol	Description	GBPC 1005	GBPC 101	GBPC 102	GBPC 104	GBPC 106	GBPC 108	GBPC 110	Unit	Conditions
V <sub>F</sub>	Max Instantaneous Forward Voltage	1.0							V	Drop per Bridge element 1.5A
I <sub>R</sub>	Max DC Reverse Current at Rated DC Blocking Voltage	5.0							µA	TA=25°C
		500								Tc=125°C
C <sub>J</sub>	Typical Junction Capacitance	/			/				pF	/
Rθ-Ja	Typical Thermal Resistance	8.0							°C/W	Note 1
Rθ-JI		12								

#### Note:

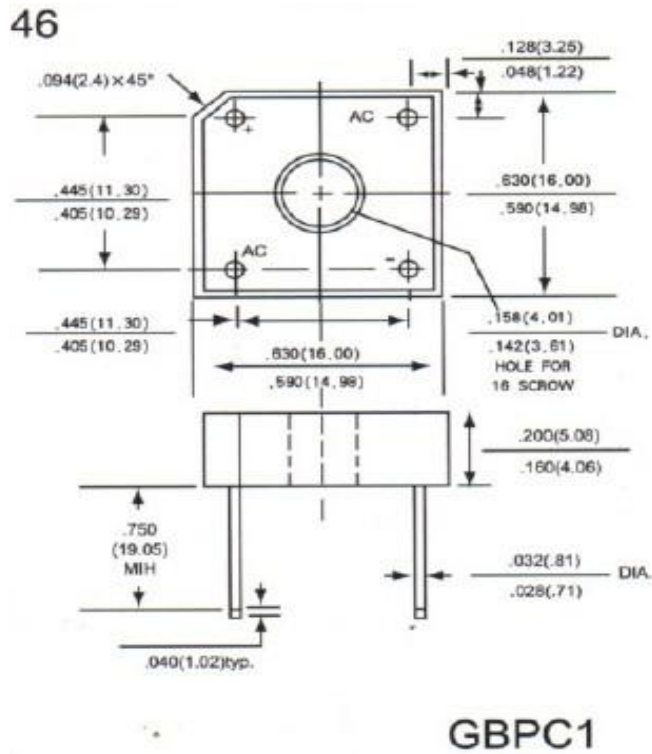
1. Bolt down on heatsink with silicon thermal compound between bridge and mounting surface for maximum heat transfer with #6 screw.
2. Unit mounted on 4.0" x 4.0" x 0.11" thick (10.5 x 10.5 x 0.3cm) Al Plate
3. Unit mounted on P.C.B at 0.375" (9.5mm) lead with 0.5"x 0.5"(12x12mm) copper pads

## GBPC1005 ~ GBPC110 RATINGS AND CHARACTERISTIC CURVES GBL05 THRU GBL10

**FIG. 1 - DERATING CURVE OUTPUT RECTIFIED CURRENT**

**FIG. 2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG**

**FIG. 3 - TYPICAL FORWARD CHARACTERISTICS PER LEG**

**FIG. 4 - TYPICAL REVERSE LEAKAGE CHARACTERISTICS PER LEG**

**FIG. 5 - TYPICAL JUNCTION CAPACITANCE PER LEG**

**FIG. 6 - TYPICAL TRANSIENT THERMAL IMPEDANCE PER LEG**


**GBPC1005 ~ GBPC110**

Dimensions in inches (mm)



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